

DESCRIPTION

The fundamental of SP6012 synchronous rectifier (SR) driver IC is based on our U.S. patented methods that utilize the principle of "prediction" logic circuit. The IC deliberates previous cycle timing to control the SR in present cycle by "predictive" algorithm that makes adjustments to the turn-off time, in order to achieve maximum efficiency and avoid cross-conduction at the same time. It also maintains the MOSFET's body diode conduction at minimum level. The SP6012 is capable to adapt in almost all existing forward converters with few adjustments considered necessary.

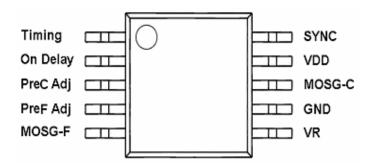
APPLICATIONS

- Servers & workstations
- Storage area network power supplies
- Telecommunication converters
- Embedded systems
- Industrial & commercial systems using high current processors

FEATURES

- Offers 4 to 8% efficiency improvement over Schottky Diodes (depend on drive configuration of the SR).
- Drives all level Power MOSFET.
- Prediction gate timing control.
- Minimum MOSFET body diode conduction.
- Operating frequency up to 650 KHz.
- Synchronize to transformer secondary voltage waveform.

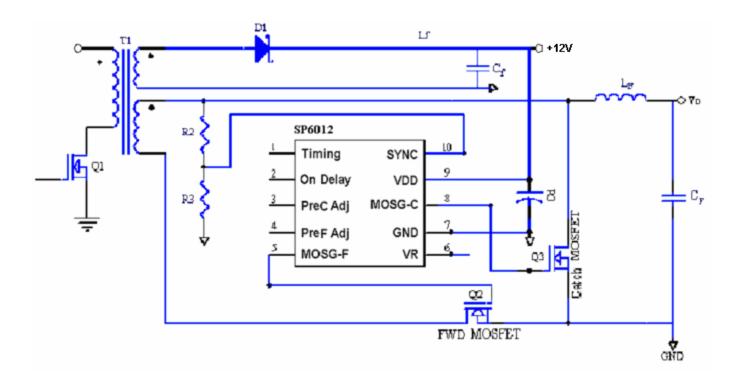
PIN CONFIGURATION (SOP-10P)



PART MARKING (SOP-10P)



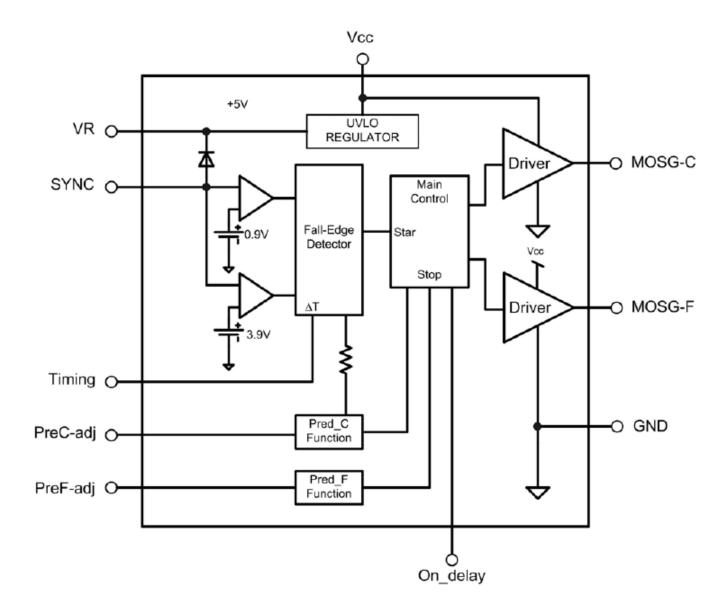
TYPICAL APPLCATION CIRCUIT



PIN DESCRIPTION

Pin	Symbol	Description	
1	Timing	Discontinuous current filter timing adjustment resistor connection.	
2	On Delay	Imposed delay between Catch gate turn OFF and Forward gate turn ON.	
3	PreC Adj	Capacitor to store previous cycle timing for Catch MOSFET	
4	PreF Adj	Capacitor to store previous cycle timing for Forward MOSFET	
5	MOSG-F	Forward MOSFET gate drive.	
6	VR	Voltage Regulator	
7	GND	Ground connection.	
8	MOSG-C	Catch MOSFET gate drive.	
9	Vdd	DC supply voltage.	
10	SYNC	Synchronized signal from transformer's output.	

BLOCK DIAGRAM



ORDERING INFORMATION

Part Number	Package	Part Marking
SP6012S10RG	SOP-10P	SP6012 I

% SP6012S10RG: 7" Tape Reel; Pb – Free



ABSOULTE MAXIMUM RATINGS (T_A=25°C, unless otherwise specified.)

The following ratings designate persistent limits beyond which damage to the device may occur.

Symbol	Parameter	Value	Unit
$V_{ m dd}$	DC Supply Voltage	17	V
SYNC	SYNC Voltage	7	V
I_{OUT}	Peak Source Current (Pulsed)	3	Α
	Peak Sink Current (Pulsed)	3	A
P_{D}	Power Dissipation @ $T_A=85^{\circ}C$ (*)	0.25	W
T_{J}	Operating Junction Temperature Range	-40 to125	$^{\circ}\! C$
T_{STG}	Storage Temperature Range	-40 to 150	$^{\circ}\! \mathbb{C}$
T_{LEAD}	Lead Soldering Temperature for 5 sec.	260	$^{\circ}\! C$

THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
Rөjc	Thermal Resistance Junction – Case (*)	45	°C/W

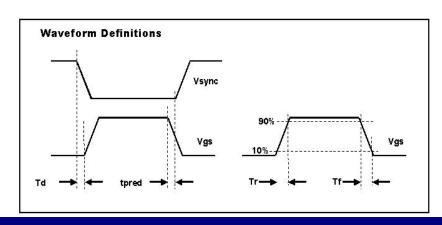
^(*) The power dissipation and thermal resistance are evaluated under copper board mounted with free air conditions.

ELECTRICAL CHARACTERISTICS

(T_A=25°C, V_{dd}=12V, Freq. =300 KHz, Duty Cycle=50%, unless otherwise specified.)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
UPPLY IN	PUT					
Idd	Supply current	No load		10		mA
		V _{SYNC} =0V, No load		10	15	mA
Vonth	Vdd turn on threshold			9.5	10	V
Voffth	Vdd turn off threshold		8	8.5		V
SYNC REFI	ERENCE (SYNC)					
Vshth	SYNC high threshold		3.9	5.0		V
Vslth	SYNC low threshold			0.9	1.2	V
MOSFET G	ATE DRIVER (MOSG-C)					
Voh	Output high voltage	Io = -200mA	11.5	11.8		V
Vol	Output low voltage	Io = 200mA		0.1	0.2	V
Td	Propagation delay	No load		50		ns
Tpred		No load		120		ns
Tr	Rise time	Load = 1nF(*)		50	100	ns
Tf	Fall time	Load = 1nF(*)		35	60	ns

^(*) Tr & Tf are measured among 10% and 90% of starting and final voltage.



PERFORMANCE CHARACTERISTICS (T_A=25°C, unless otherwise specified.)

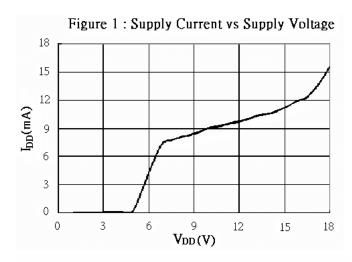
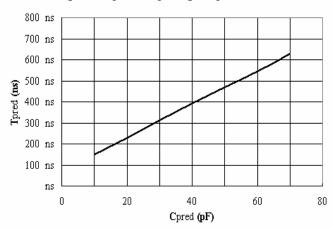
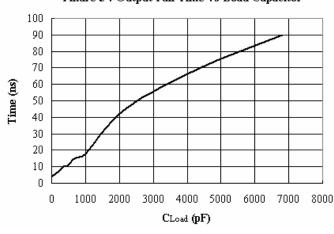


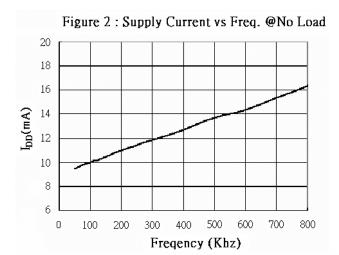
Figure 3 : Tpred vs Cpred @ Freq = 70 KHz ; V_{DD} =10V



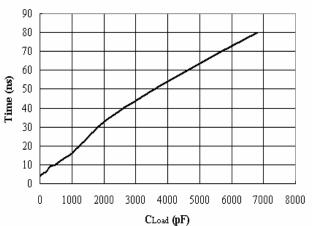
Fihure 5: Output Fall Time vs Load Capacitor



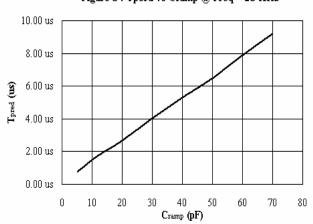
*Fig. 1 : No Load ; No SYNC *Fig. 4~5 : Frequency = 65 kHz.



Fihure 4: Output Rise Time vs Load Capacitor

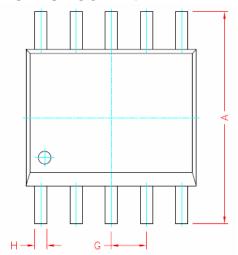


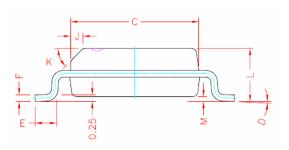


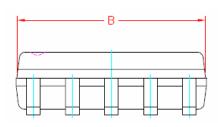




SOP- 10P PACKAGE OUTLINE







	DIMENSIONS		
REF.	Millimeters		
	Min.	Max.	
Α	5.80	6.20	
В	4.80	5.00	
С	3.80	4.00	
D	0°	8*	
Ε	0.40	0.90	
F	0.19	0.25	
М	0.10	0.25	
Н	0.30	0.44	
L	1.35	1.75	
J	0.375 REF.		
K	45°		
G	1.00 TYP.		



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